## ABSTRACT

### METHOD FOR ATTACHING SOLDER BALLS ONTO WAFER AND APPARATUS THEREFOR

Disclosed herewith is a method for attaching solder balls onto a wafer. The method includes a preliminary surface inspection step in which a surface of a wafer onto which solder balls are attached is preliminary inspected and data obtained by the inspection is transmitted to a control unit. Thereafter, there is performed a solder ball suction step in which a plurality of solder balls are sucked into a plurality of sucking holes formed in a sucking plate. Finally, there follow a solder ball attachment step in which solder balls in the sucking holes of the attachment plate are supplied onto the wafer. In such a case, the solder ball suction step and the solder ball attachment step are alternately repeated section-by-section on a single wafer. Additionally, an apparatus for attaching solder balls onto a wafer is also disclosed.

(Please note that Figure 1 shoule accompany the abstract when published)